



Product Change Notification / GBNG-30ZMTP819

Date:

23-Feb-2021

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4284 Initial Notice: Qualification of GTK as a new assembly site for selected SST39VF640xxx and SST39VF320xxx device families available in 48L TSOP (12x20mm) package.

Affected CPNs:

[GBNG-30ZMTP819_Affected_CPN_02232021.pdf](#)

[GBNG-30ZMTP819_Affected_CPN_02232021.csv](#)

Notification Text:

PCN Status: Initial notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of GTK as a new assembly site for selected SST39VF640xxx and SST39VF320xxx device families available in 48L TSOP (12x20mm) package.

Pre Change: Assembled at LPI using 8340 die attach, G700 molding compound material, 276 x 350 or 190 x 250 mils paddle size and double ring plating DAP Surface Prep.

Post Change: Assembled at GTK using EN-4900GC die attach, G600F molding compound material, 330 x 260 mils paddle size and ring plating DAP Surface Prep.

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	Lingsen Precision Industries, LTD. (LPI)		Greatek Electronic Inc. (GTK)
Wire material	Au		Au
Die attach material	8340		EN-4900GC
Molding compound material	G700		G600F
Lead frame material	C7025		C7025
Paddle size	276 x 350 mils	190 x 250 mils	330 x 260 mils
DAP Surface Prep	Double ring plating		Ring plating
Lead Lock (Locking Hole)	No		No

Impacts to Data Sheet: None**Change Impact:** None**Reason for Change:** To improve on-time delivery performance by qualifying GTK as a new assembly site.**Change Implementation Status:** In Progress**Estimated Qualification Completion Date:** February 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	July 2020					>	February 2021			
Workweek	27	28	29	30	31		06	07	08	09
Initial PCN Issue Date	X									
Qual Report Availability										X
Final PCN Issue Date										X

Method to Identify Change: Traceability code**Qualification Plan:** Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: July 02, 2020: Issued initial notification. **February 23, 2021:** Re-issued initial notification. Added SST39VF320xxx device family in notification subject, description of change and affected CPN list. Updated the qual plan title and purpose. Added paddle size, DAP surface PREP and lead lock information in Pre and Post change description and table summary.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_GBNG-30ZMTP819_Qual_Plan.pdf](#)

[PCN_GBNG-30ZMTP819_Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.